

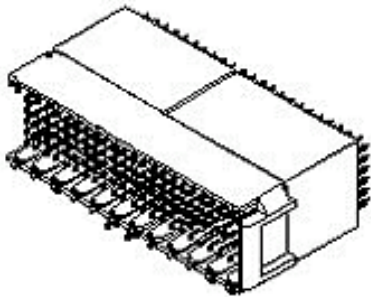
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Part Number: [0737701200](#)
Status: **Active**
Overview: [HDM Backplane Connector System](#)
Description: HDM Board-to-Board Stacking Header, High Rise Vertical, SMC, Closed End Option, 144 Circuits, Stack Height 6.05mm

Documents:
[3D Model](#)
[Drawing \(PDF\)](#)
[Product Specification PS-73780-999-001 \(PDF\)](#)
[Packaging Specification PK-70873-0875 \(PDF\)](#)
[RoHS Certificate of Compliance \(PDF\)](#)

Agency Certification	
CSA	LR19980
UL	E29179
General	
Product Family	Backplane Connectors
Series	73770
Application	Backplane, Mezzanine
Component Type	PCB Header
Overview	HDM Backplane Connector System
Product Name	HDM
UPC	800754828963

Physical	
Circuits (Loaded)	144
Circuits (maximum)	144
Color - Resin	Black
Durability (mating cycles max)	200
First Mate / Last Break	No
Flammability	94V-0
Guide to Mating Part	No
Keying to Mating Part	None
Material - Metal	Phosphor Bronze
Material - Plating Mating	Gold
Material - Plating Termination	Tin-Lead
Material - Resin	High Temperature Thermoplastic
Net Weight	13.735/g
Number of Columns	24
Number of Pairs	Open Pin Field
Number of Rows	6
Orientation	Vertical
PC Tail Length	3.50mm
PCB Locator	No
PCB Retention	None
PCB Thickness - Recommended	1.40mm
Packaging Type	Tube
Pitch - Mating Interface	2.00mm
Pitch - Termination Interface	2.00mm
Plating min - Mating	0.762µm
Plating min - Termination	0.381µm
Polarized to PCB	No
Stackable	Yes
Surface Mount Compatible (SMC)	Yes
Temperature Range - Operating	-55° to +105°C
Termination Interface: Style	Through Hole - Compliant Pin



Series image - Reference only

EU ELV Not Relevant	
EU RoHS Compliant REACH SVHC Not Contained Per - ED/71/2019 (16 July 2019) Halogen-Free Status Low-Halogen For more information, please visit Contact US	China RoHS China ROHS ELV RoHS Phthalates
	Green Image Not Relevant Not Contained

Search Parts in this Series
[73770](#) Series

Mates With
[73632](#) HDM+ Board-to-Board Daughtercard Receptacle. [73780](#) HDM Board-to-Board Daughtercard Receptacle

Application Tooling | FAQ
Tooling specifications and manuals are found by selecting the products below. Crimp Height Specifications are then contained in the Application Tooling Specification document.

Global	
Description	Product #
Extraction Tool	621001000
Backplane Insertion	621001400
Signal Contact Tool	
Backplane Insertion	622005703
Head for 144 Circuits	

Electrical

Current - Maximum per Contact	1.0A
Data Rate	1.0 Gbps
Real Signals (per 25mm)	72
Voltage - Maximum	250V AC

Solder Process Data

Lead-freeProcess Capability	N/A
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Material Info

Reference - Drawing Numbers

Packaging Specification	PK-70873-0875
Product Specification	PS-73780-999-001
Sales Drawing	SD-73770-001

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